IEEE P802.11  
Wireless LANs

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| TGbe Sept-Nov Teleconference Minutes | | | | |
| Date: 2022-10-12 | | | | |
| Author(s): | | | | |
| Name | Affiliation | Address | Phone | email |
| Jason Yuchen Guo | Huawei |  |  | guoyuchen@huawei.com |
|  |  |  |  |  |
|  |  |  |  |  |

Abstract

This document contains the minutes for the IEEE 802.11 TGbe teleconferences from September to November 2022.

Revision history:

* Rev0: initial version of the document
* Rev1: add the minutes for the October 26 (10:00–12:00 ET)–JOINT Conf. Call, and add the links for the MAC ad hoc Conf. calls on Sept 28, Oct 13, Oct 17, Oct 19

Abbreviations:

* C: Comment.
* A: Answer.

# 1st Conf. Call: September 26 (19:00–21:00 ET)–PHY

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-1667-00-00be-minutes-802-11be-phy-ad-hoc-september-to-november-conference-calls.docx

# 1st Conf. Call: September 26 (19:00–21:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-1668-00-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-september-and-november-2022.docx

# 2nd Conf. Call: September 28 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-1668-01-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-september-and-november-2022.docx

# 3rd Conf. Call: October 12 (10:00–12:00 ET)–JOINT

* The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order
* The Chair presents the IEEE 802 and 802.11 IPR policy and procedure
  + **Patent Policy: Ways to inform IEEE:**
    - Cause an LOA to be submitted to the IEEE-SA ([patcom@ieee.org](mailto:patcom@ieee.org)); or
    - Provide the chair of this group with the identity of the holder(s) of any and all such claims as soon as possible; or
    - Speak up now and respond to this Call for Potentially Essential Patents

If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group and that are not already the subject of an Accepted Letter of Assurance, please respond at this time by providing relevant information to the WG Chair. **Nobody speaks/writes up**.

* + **Copyright Policy: Participants are advised that**
    - IEEE SA’s copyright policy is described in [Clause 7](https://standards.ieee.org/about/policies/bylaws/sect6-7.html#7) of the IEEE SA Standards Board Bylaws and [Clause 6.1](https://standards.ieee.org/about/policies/opman/sect6.html) of the IEEE SA Standards Board Operations Manual;
    - Any material submitted during standards development, whether verbal, recorded, or in written form, is a Contribution and shall comply with the IEEE SA Copyright Policy

**Copyright Policy was presented.**

* + **Patent, Participation, Copyright and policy related subclause:** Please refer to Patent And Procedures
* Attendance reminder.
  + Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
  + Please record your attendance during the conference call by using the IMAT system:
    - 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “<Joint TGbe > conference call that you are attending.
  + If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Jason Y. Guo ([guoyuchen@huawei.com](mailto:guoyuchen@huawei.com)) and Alfred Asterjadhi ([asterjadhi@gmail.com](mailto:asterjadhi@gmail.com))
  + Please ensure that the following information is listed correctly when joining the call:
    - "[voter status] First Name Last Name (Affiliation)"
  + Attendee List

|  |  |  |  |
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| Breakout | Timestamp | Name | Affiliation |
| TGbe (Joint) | 10/12 | Adhikari, Shubhodeep | Broadcom Corporation |
| TGbe (Joint) | 10/12 | Ajami, Abdel Karim | Qualcomm Incorporated |
| TGbe (Joint) | 10/12 | Asterjadhi, Alfred | Qualcomm Incorporated |
| TGbe (Joint) | 10/12 | Baek, SunHee | LG ELECTRONICS |
| TGbe (Joint) | 10/12 | Bahn, Christy | IEEE STAFF |
| TGbe (Joint) | 10/12 | baron, stephane | Canon Research Centre France |
| TGbe (Joint) | 10/12 | Bredewoud, Albert | Broadcom Corporation |
| TGbe (Joint) | 10/12 | Cao, Rui | NXP Semiconductors |
| TGbe (Joint) | 10/12 | Carney, William | Sony Group Corporation |
| TGbe (Joint) | 10/12 | Chen, You-Wei | MediaTek Inc. |
| TGbe (Joint) | 10/12 | Cheng, Xilin | NXP Semiconductors |
| TGbe (Joint) | 10/12 | CHENG, yajun | Xiaomi Communications Co., Ltd. |
| TGbe (Joint) | 10/12 | CHERIAN, GEORGE | Qualcomm Incorporated |
| TGbe (Joint) | 10/12 | Chitrakar, Rojan | Panasonic Asia Pacific Pte Ltd. |
| TGbe (Joint) | 10/12 | CHUN, JINYOUNG | LG ELECTRONICS |
| TGbe (Joint) | 10/12 | Chung, Chulho | SAMSUNG |
| TGbe (Joint) | 10/12 | Dong, Xiandong | Xiaomi Inc. |
| TGbe (Joint) | 10/12 | Duan, Ruchen | SAMSUNG |
| TGbe (Joint) | 10/12 | Erkucuk, Serhat | Ofinno |
| TGbe (Joint) | 10/12 | Fan, Shuang | ZTE Corporation |
| TGbe (Joint) | 10/12 | Fang, Yonggang | Mediatek |
| TGbe (Joint) | 10/12 | Fischer, Matthew | Broadcom Corporation |
| TGbe (Joint) | 10/12 | Fujimori, Yuki | Canon Research Centre France |
| TGbe (Joint) | 10/12 | Ghosh, Chittabrata | Meta Platforms; PWC, LLC |
| TGbe (Joint) | 10/12 | Gorthi, Hemamali | Infineon Technologies |
| TGbe (Joint) | 10/12 | Gu, Xiangxin | Unisoc |
| TGbe (Joint) | 10/12 | Guo, Yuchen | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/12 | Haider, Muhammad Kumail | Facebook |
| TGbe (Joint) | 10/12 | Handte, Thomas | Sony Corporation |
| TGbe (Joint) | 10/12 | Hart, Brian | Cisco Systems, Inc. |
| TGbe (Joint) | 10/12 | Hervieu, Lili | Cable Television Laboratories Inc. (CableLabs) |
| TGbe (Joint) | 10/12 | Hu, Chunyu | Facebook |
| TGbe (Joint) | 10/12 | Huang, Lei | Huawei International Pte Ltd |
| TGbe (Joint) | 10/12 | Huang, Po-Kai | Intel |
| TGbe (Joint) | 10/12 | Huq, Kazi Mohammed Saidul | Ofinno |
| TGbe (Joint) | 10/12 | Jang, Insun | LG ELECTRONICS |
| TGbe (Joint) | 10/12 | Jung, Insik | LG ELECTRONICS |
| TGbe (Joint) | 10/12 | Kain, Carl | USDoT; Noblis, Inc. |
| TGbe (Joint) | 10/12 | Kamel, Mahmoud | InterDigital, Inc. |
| TGbe (Joint) | 10/12 | Kim, Jeongki | Ofinno |
| TGbe (Joint) | 10/12 | Kim, Sang Gook | LG ELECTRONICS |
| TGbe (Joint) | 10/12 | Kim, Sanghyun | WILUS Inc |
| TGbe (Joint) | 10/12 | Kishida, Akira | Nippon Telegraph and Telephone Corporation (NTT) |
| TGbe (Joint) | 10/12 | Ko, Geonjung | WILUS Inc. |
| TGbe (Joint) | 10/12 | Lalam, Massinissa | SAGEMCOM BROADBAND SAS |
| TGbe (Joint) | 10/12 | Lanante, Leonardo | Ofinno |
| TGbe (Joint) | 10/12 | Levy, Joseph | InterDigital, Inc. |
| TGbe (Joint) | 10/12 | Li, Yapu | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint) | 10/12 | Lim, Dong Guk | LG ELECTRONICS |
| TGbe (Joint) | 10/12 | Lorgeoux, Mikael | Canon Research Centre France |
| TGbe (Joint) | 10/12 | Lou, Hanqing | InterDigital, Inc. |
| TGbe (Joint) | 10/12 | Lu, Liuming | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint) | 10/12 | Ma, Yunsi | HiSilicon (Shanghai) Technologies Co., LTD. |
| TGbe (Joint) | 10/12 | MAO, ZHI | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/12 | McCann, Stephen | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/12 | Mehrnoush, Morteza | Facebook |
| TGbe (Joint) | 10/12 | NANDAGOPALAN, SAI SHANKAR | Synaptics |
| TGbe (Joint) | 10/12 | Nayak, Peshal | Samsung Research America |
| TGbe (Joint) | 10/12 | Nezou, Patrice | Canon Research Centre France |
| TGbe (Joint) | 10/12 | Ng, Boon Loong | Samsung Research America |
| TGbe (Joint) | 10/12 | Orr, Stephen | Cisco Systems, Inc. |
| TGbe (Joint) | 10/12 | Ouchi, Masatomo | Canon |
| TGbe (Joint) | 10/12 | Park, Minyoung | Intel |
| TGbe (Joint) | 10/12 | Park, Sungjin | Senscomm |
| TGbe (Joint) | 10/12 | Patil, Abhishek | Qualcomm Incorporated |
| TGbe (Joint) | 10/12 | Patwardhan, Gaurav | Hewlett Packard Enterprise |
| TGbe (Joint) | 10/12 | Qi, Yue | Samsung Research America |
| TGbe (Joint) | 10/12 | Ryu, Kiseon | NXP Semiconductors |
| TGbe (Joint) | 10/12 | Schelstraete, Sigurd | MaxLinear |
| TGbe (Joint) | 10/12 | Sevin, Julien | Canon Research Centre France |
| TGbe (Joint) | 10/12 | Shafin, Rubayet | Samsung Research America |
| TGbe (Joint) | 10/12 | Shellhammer, Stephen | Qualcomm Incorporated |
| TGbe (Joint) | 10/12 | Sherlock, Ian | Texas Instruments Inc. |
| TGbe (Joint) | 10/12 | Shirakawa, Atsushi | SHARP CORPORATION |
| TGbe (Joint) | 10/12 | Stanley, Dorothy | Hewlett Packard Enterprise |
| TGbe (Joint) | 10/12 | SUH, JUNG HOON | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/12 | Taori, Rakesh | Infineon Technologies |
| TGbe (Joint) | 10/12 | Tsujimaru, Yuki | Canon Inc. |
| TGbe (Joint) | 10/12 | Varshney, Prabodh | Nokia |
| TGbe (Joint) | 10/12 | Verenzuela, Daniel | Sony Corporation |
| TGbe (Joint) | 10/12 | Wang, Chao Chun | MediaTek Inc. |
| TGbe (Joint) | 10/12 | Wang, Hao | Tencent |
| TGbe (Joint) | 10/12 | Wang, Qi | Apple, Inc. |
| TGbe (Joint) | 10/12 | Wei, Dong | NXP Semiconductors |
| TGbe (Joint) | 10/12 | Wullert, John | Peraton Labs |
| TGbe (Joint) | 10/12 | Yang, Jay | Nokia |
| TGbe (Joint) | 10/12 | Yano, Kazuto | Advanced Telecommunications Research Institute International (ATR) |
| TGbe (Joint) | 10/12 | Yi, Yongjiang | Spreadtrum Communication USA, Inc |
| TGbe (Joint) | 10/12 | Zhou, Pei | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |

* Announcements:
  + POCs are requested to perform a status check of CR documents/pending CIDs.
  + CIDs in quarantine (see [984r14](https://mentor.ieee.org/802.11/dcn/20/11-20-0984-14-00be-tgbe-teleconference-guidelines.docx) for guidelines, and [971r24](https://mentor.ieee.org/802.11/dcn/22/11-22-0971-24-00be-ieee-802-11be-lb266-comments.xlsx) for latest LB266 database) will start to be added to quarantine motions from this Friday, 14th of October 2022.
* Agenda
  + Technical Submissions**: CRs**
    - [1317r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1317-02-00be-cr-on-cid-10116.docx) CR on CID 10116 Bo Gong [1C-SP 10’]
    - [1565r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1565-01-00be-lb266-cr-for-uora.docx) LB266 CR for UORA Greg Geonjung Ko [8C-SP 10’]
    - [1531r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1531-00-00be-lb266-cr-for-cid-14051.docx) CR for CID 14051 Ruchen Duan [1C 15’]
    - [1468r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1468-00-00be-cr-for-cids-in-35-7.docx) CR for CIDs in 35.7 Zinan Lin [5C 15’]
    - [1726r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1726-00-00be-lb266-cr-for-cid-12064.docx) CR for CID 12064 Leonardo Lanante [1C 10’]
    - *Any CRs from MAC queues?*
  + Technical Submissions:
    - [1423r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1423-00-00be-eht-smps.docx) EHT SMPS Xiaogang Chen [PDT 15’]
  + Discussions
    - 1307r2 was requested to be added to the SP list
    - 1509r3 from MAC was requested to be added to the contribution list
  + Agenda approved with unanimous consent
* Discussions of the Technical Submissions**: CRs**
  + [1317r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1317-02-00be-cr-on-cid-10116.docx) CR on CID 10116 Bo Gong

C: Regarding the last comment, the figure is not applicable to the solicited MFB

C: Defer the SP for offline discussion.

C: the current text in this document does not touch the SP regarding defining EHT link adaptation in R2.

The presenter decides to run the SP.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1317r2 and incorporate the text changes into the latest TGbe draft?

         10116, 11677, 10788, 13535

Discussion: None.

Result: 31Y, 19N, 42A

* + [1565r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1565-01-00be-lb266-cr-for-uora.docx) LB266 CR for UORA Greg Geonjung Ko

C: if we use HE RA RU, we don’t need to care about the fairness issue, hence I still think using the HE RA RU is a better choice.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1565r1 and incorporate the text changes into the latest TGbe draft?



Discussion: None.

Result: 29Y, 20N, 27A

* + 1307r2 cr-for-9.3.1.19-part1 Jinyoung Chun

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1307r2 and incorporate the text changes into the latest TGbe draft?

         11683

Discussion: None.

Result: No objection.

* + [1531r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1531-00-00be-lb266-cr-for-cid-14051.docx) CR for CID 14051 Ruchen Duan

C: we should be really careful adding this change to the BlockAck at this stage.

C: I think we may find a simple method, e.g., BA can be aggregated with QoS null frame as an A-MPDU in a single PPDU.

No SP was run.

* + [1468r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1468-00-00be-cr-for-cids-in-35-7.docx) CR for CIDs in 35.7 Zinan Lin

C: in the NOTE in P506L26, change “is” to “might”

C:11274, the resolution should be revised since the modification is not exactly the same as the proposed change.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1468r1 and incorporate the text changes into the latest TGbe draft?

        11274, 11275, 11663, 11669, 11670

Discussion: None.

Result: No objection.

* + [1726r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1726-00-00be-lb266-cr-for-cid-12064.docx) CR for CID 12064 Leonardo Lanante

C: in the baseline spec, we have languages describing that multiple links can access independently, I think the languages here can be largely simplified.

C: using a note will be a better choice.

C: Agree with Yanjun, we can have simplified languages.

* + 1509r3 MLD Load Balancing Pooya Monajemi

C: there are several changes, better to outline what are the mandatory behaviors, how negoatiable is this really? If AP strongly suggest, how would the sequence go?

C: what happens if the non-AP STA declines?

C: we’ve already have a scheme for load balancing which is BTM where STA does not have flexibility, the proposed scheme is a more balanced one.

C: the name of the field “Priority” is not very clear, “negotiability” could be better.

C: Table 9-xx1, last collum, need to remove the broadcast part.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1509r4 and incorporate the text changes into the latest TGbe draft?

        14055, 10488, 11106, 11108, 11763, ~~12632~~

Discussion: None.

Result: 52Y, 34N, 28A

* Adjourned at 11:58

# 4th Conf. Call: October 13 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-1668-01-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-september-and-november-2022.docx

# 5th Conf. Call: October 17 (19:00–21:00 ET)–PHY

Please refer to the following link for the minutes

* to be added

# 5th Conf. Call: October 17 (19:00–21:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-1668-01-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-september-and-november-2022.docx

# 6th Conf. Call: October 19 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-1668-01-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-september-and-november-2022.docx

# 7th Conf. Call: October 26 (10:00–12:00 ET)–JOINT

* The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order
* The Chair presents the IEEE 802 and 802.11 IPR policy and procedure
  + **Patent Policy: Ways to inform IEEE:**
    - Cause an LOA to be submitted to the IEEE-SA ([patcom@ieee.org](mailto:patcom@ieee.org)); or
    - Provide the chair of this group with the identity of the holder(s) of any and all such claims as soon as possible; or
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    - Any material submitted during standards development, whether verbal, recorded, or in written form, is a Contribution and shall comply with the IEEE SA Copyright Policy
    - **Copyright Policy was presented.**
  + **Patent, Participation, Copyright and policy related subclause:** Please refer to Patent And Procedures
* Attendance reminder.
  + Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
  + Please record your attendance during the conference call by using the IMAT system:
    - 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “<Joint TGbe > conference call that you are attending.
  + If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Jason Y. Guo ([guoyuchen@huawei.com](mailto:guoyuchen@huawei.com)) and Alfred Asterjadhi ([asterjadhi@gmail.com](mailto:asterjadhi@gmail.com))
  + Please ensure that the following information is listed correctly when joining the call:
    - "[voter status] First Name Last Name (Affiliation)"
  + Attendee List

|  |  |  |  |
| --- | --- | --- | --- |
| Breakout | Timestamp | Name | Affiliation |
| TGbe (Joint) | 10/26 | Aboulmagd, Osama | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Ajami, Abdel Karim | Qualcomm Incorporated |
| TGbe (Joint) | 10/26 | Ansley, Carol | Cox Communications Inc. |
| TGbe (Joint) | 10/26 | Au, Kwok Shum | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Baek, SunHee | LG ELECTRONICS |
| TGbe (Joint) | 10/26 | Bahn, Christy | IEEE STAFF |
| TGbe (Joint) | 10/26 | baron, stephane | Canon Research Centre France |
| TGbe (Joint) | 10/26 | Baykas, Tuncer | Ofinno |
| TGbe (Joint) | 10/26 | Bredewoud, Albert | Broadcom Corporation |
| TGbe (Joint) | 10/26 | Carney, William | Sony Group Corporation |
| TGbe (Joint) | 10/26 | CHENG, yajun | Xiaomi Communications Co., Ltd. |
| TGbe (Joint) | 10/26 | Chitrakar, Rojan | Panasonic Asia Pacific Pte Ltd. |
| TGbe (Joint) | 10/26 | Chu, Liwen | NXP Semiconductors |
| TGbe (Joint) | 10/26 | Chung, Chulho | SAMSUNG |
| TGbe (Joint) | 10/26 | Das, Subir | Peraton Labs |
| TGbe (Joint) | 10/26 | Dong, Xiandong | Xiaomi Communications Co., Ltd. |
| TGbe (Joint) | 10/26 | Du, Rui | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Erkucuk, Serhat | Ofinno |
| TGbe (Joint) | 10/26 | Fan, Shuang | ZTE Corporation |
| TGbe (Joint) | 10/26 | Fang, Yonggang | Mediatek |
| TGbe (Joint) | 10/26 | Fischer, Matthew | Broadcom Corporation |
| TGbe (Joint) | 10/26 | Gan, Ming | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Gu, Xiangxin | Unisoc |
| TGbe (Joint) | 10/26 | Guo, Yuchen | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Gupta, Binita | Meta Platforms, Inc. |
| TGbe (Joint) | 10/26 | Handte, Thomas | Sony Corporation |
| TGbe (Joint) | 10/26 | Hervieu, Lili | Cable Television Laboratories Inc. (CableLabs) |
| TGbe (Joint) | 10/26 | Hu, Chunyu | Facebook |
| TGbe (Joint) | 10/26 | Huang, Guogang | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Huang, Lei | Huawei International Pte Ltd |
| TGbe (Joint) | 10/26 | Huq, Kazi Mohammed Saidul | Ofinno |
| TGbe (Joint) | 10/26 | Ji, Chenhe | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Jung, Insik | LG ELECTRONICS |
| TGbe (Joint) | 10/26 | Kakani, Naveen | Qualcomm Incorporated |
| TGbe (Joint) | 10/26 | Kim, Sang Gook | LG ELECTRONICS |
| TGbe (Joint) | 10/26 | Kim, Sanghyun | WILUS Inc |
| TGbe (Joint) | 10/26 | Kim, Youhan | Qualcomm Incorporated |
| TGbe (Joint) | 10/26 | Klein, Arik | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Ko, Geonjung | WILUS Inc. |
| TGbe (Joint) | 10/26 | Lalam, Massinissa | SAGEMCOM BROADBAND SAS |
| TGbe (Joint) | 10/26 | Lee, Wookbong | SAMSUNG |
| TGbe (Joint) | 10/26 | Li, Yapu | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
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| TGbe (Joint) | 10/26 | MAO, ZHI | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | McCann, Stephen | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Montemurro, Michael | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Naik, Gaurang | Qualcomm Incorporated |
| TGbe (Joint) | 10/26 | NANDAGOPALAN, SAI SHANKAR | Synaptics |
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| TGbe (Joint) | 10/26 | Patwardhan, Gaurav | Hewlett Packard Enterprise |
| TGbe (Joint) | 10/26 | Peng, Lan | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Petrick, Albert | InterDigital, Inc. |
| TGbe (Joint) | 10/26 | Qi, Yue | Samsung Research America |
| TGbe (Joint) | 10/26 | Quan, Yingqiao | Unisoc |
| TGbe (Joint) | 10/26 | Ratnam, Vishnu | Samsung Research America |
| TGbe (Joint) | 10/26 | Ryu, Kiseon | NXP Semiconductors |
| TGbe (Joint) | 10/26 | Schelstraete, Sigurd | MaxLinear |
| TGbe (Joint) | 10/26 | Shafin, Rubayet | Samsung Research America |
| TGbe (Joint) | 10/26 | Sherlock, Ian | Texas Instruments Inc. |
| TGbe (Joint) | 10/26 | Shilo, Shimi | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Shu, Tongxin | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | SU, HONGJIA | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | SUH, JUNG HOON | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Sun, Bo | ZTE Corporation |
| TGbe (Joint) | 10/26 | Sun, Yanjun | Qualcomm Incorporated |
| TGbe (Joint) | 10/26 | Taori, Rakesh | Infineon Technologies |
| TGbe (Joint) | 10/26 | Tsodik, Genadiy | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Tsujimaru, Yuki | Canon Inc. |
| TGbe (Joint) | 10/26 | Varshney, Prabodh | Nokia |
| TGbe (Joint) | 10/26 | Verenzuela, Daniel | Sony Corporation |
| TGbe (Joint) | 10/26 | Vermani, Sameer | Qualcomm Incorporated |
| TGbe (Joint) | 10/26 | Wang, Chao Chun | MediaTek Inc. |
| TGbe (Joint) | 10/26 | Wang, Hao | Tencent |
| TGbe (Joint) | 10/26 | Wang, Qi | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Wei, Dong | NXP Semiconductors |
| TGbe (Joint) | 10/26 | Wu, Kanke | Qualcomm Incorporated |
| TGbe (Joint) | 10/26 | Wu, Tianyu | Apple, Inc. |
| TGbe (Joint) | 10/26 | Wullert, John | Peraton Labs |
| TGbe (Joint) | 10/26 | Yang, Steve TS | MediaTek Inc. |
| TGbe (Joint) | 10/26 | Yano, Kazuto | Advanced Telecommunications Research Institute International (ATR) |
| TGbe (Joint) | 10/26 | Yee, James | MediaTek Inc. |
| TGbe (Joint) | 10/26 | Yi, Yongjiang | Spreadtrum Communication USA, Inc |
| TGbe (Joint) | 10/26 | Yoon, Yelin | LG ELECTRONICS |
| TGbe (Joint) | 10/26 | Yu, Jian | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 10/26 | Zhang, Jiayi | Ofinno |
| TGbe (Joint) | 10/26 | Zhou, Lei | H3C Technologies Co., Limited |

* Announcements:
  + A total of 43 MAC submissions scheduled as Pending SP for CIDs in quarantine (discussed until 17th of September but no consensus).
    - Authors are invited to check the MAC queues and ensure that everything is reflected correctly.
    - Plan is for the next 3 MAC conf calls to be used to process as many as possible (alternatively, allocate 30 mins in each of the MAC conf calls).
  + Discussion: it is suggested that the agenda be posted on mentor at least 24 hours before the meeting.
* Agenda:
  + TSN Liaison:
    - 1792r0 802.11be report on EHT functionalities in support of TSN Dave Cavalcanti [20’]
  + Technical Submissions: CRs (during first hour)
    - [1317r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1317-02-00be-cr-on-cid-10116.docx) CR on CID 10116 Bo Gong [1C-SP 10’]
    - [1726r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1726-00-00be-lb266-cr-for-cid-12064.docx) CR for CID 12064 Leonardo Lanante [1C-SP 10’]
    - [1565r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1565-02-00be-lb266-cr-for-uora.docx) LB266 CR for UORA Greg G. Ko [8C-SP 10’]
    - [1679r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1679-00-00be-comment-resolution-for-clause-35-1.docx) Comment Resolution for Clause 35.1 Osama Aboul-Magd [12C 20’]
  + Motions: [1038r16](https://mentor.ieee.org/802.11/dcn/22/11-22-1038-16-00be-tgbe-motions-list-part-3.pptx)
  + Technical Submissions: CRs (during second hour)
    - [1488r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1488-00-00be-lb266-cr-for-eht-trs-part-ii.docx) cr-for-EHT-TRS-Part-II Jason Y. Guo [13C 20’]
    - [1423r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1423-00-00be-eht-smps.docx) EHT SMPS Xiaogang Chen [1C\* 10’]
    - [1757r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1757-00-00be-lb266-cr-for-cid-13582.doc) CR for CID 13582 Ross Jian Yu [1C 10’]
    - [1363r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1363-00-00be-cr-on-3-2-cids-part2.doc) CR on 3.2 CIDs part2 Ross Jian Yu [1C 10’]
  + Discussions:
    - Xiaogang requested to present 1423r0 as the first one since it was left over from the last meeting.
    - The chair agrees to move it up as the first submission during the 2nd hour, nobody objects.
  + Agenda approved with unanimous consent
* Discussions of the TSN Liaison
  + 1792r0 802.11be report on EHT functionalities in support of TSN Dave Cavalcanti

C: Editorial reminder: R-TWT is defined as abbreviation for Restricted TWT

C: could you explain 802.1CB high levely?

A: it’s frame duplication from high layer

C: suggest to list all related features from 802.1 TSN, e.g., pre-emption, etc.

C: what’s the purpose of this document? What does 802.1 TSN do with it?

C: So it’s only for information sharing. No action needed.

C: duplication of frames is for improving reliability, how does it connect with multi-link?

C: 1CB is sending duplications MAC to MAC, for MLO, there is only one MAC SAP for an MLD. It is problematic to mention 1CB here.

C: for R-TWT you mentioned that EHT STAs are required to end its TXOP before the R-TWT SP, but for the EHT STAs that do not support the R-TWT feature, they do not end their TXOP.

* Discussions of the Technical Submissions**: CRs**
  + [1317r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1317-02-00be-cr-on-cid-10116.docx) CR on CID 10116 Bo Gong

Ross Jian Yu (Huawei) presents this submission on behalf of Bo Gong.

C: in the normative behavior, the paragraph starting with “the appearance of”, what is the difference between EHT and HE?

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1317r2 and incorporate the text changes into the latest TGbe draft?

         10116, 11677, 10788, 13535

Discussion: None.

Result: No objection.

* + [1726r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1726-00-00be-lb266-cr-for-cid-12064.docx) CR for CID 12064 Leonardo Lanante

C: isn’t the TID-to-Link mapping be applied here?

C: is the note saying OBO counting down is on the MLD level?

A: No, it’s on the link level.

C: The TID-to-Link mapping is independent of how you access the channel.

C: OBO counter is per-Link operation, why do we need to add the note?

C: for the added text in the first note, what does it mean?

* + [1565r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1565-02-00be-lb266-cr-for-uora.docx) LB266 CR for UORA Greg G. Ko

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1565r2 and incorporate the text changes into the latest TGbe draft?

        13550, 13958, 10802, 10957, 12491, 12492, 14052, 14050

Discussion: None.

Result: No objection.

* + [1679r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1679-00-00be-comment-resolution-for-clause-35-1.docx) Comment Resolution for Clause 35.1 Osama Aboul-Magd

C: do not run SP for CID 10213 separately.

* Motions: [1038r18](https://mentor.ieee.org/802.11/dcn/22/11-22-1038-18-00be-tgbe-motions-list-part-3.pptx)

The minutes for the Motions can be found from Slide 61 to Slide 69 in:

https://mentor.ieee.org/802.11/dcn/22/11-22-1038-19-00be-tgbe-motions-list-part-3.pptx

Discussion for Motion 453.

Guogang Huang (Huawei) quickly went through the document 11/22-1213r5.

C: we can not have “shall” in Clause 9

C: the number of links indicated in the MLO Link Information element should be one, why not use the Link ID, which is only 4 bits.

C: using a single Link ID field would be better.

**Results for Motion 453**

Calculated Results : 32Y, 21N, 38A, [60%]

Amended Results : 30Y, 21N, 37A, [58%]

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[V] Abdel Karim Ajami, Qualcomm | | X | |

[V] Vishnu V Ratnam, Samsung Research America | X | | |

[V] Dong Wei, NXP | | | X |

[V] Rubayet Shafin, Samsung Research America | | | X |

[V] William Carney, Sony Group | X | | |

[V] Boon Loong Ng Samsung Research America | | | X |

Ian Sherlock | X | | |

[V] Naveen Kakani, Qualcomm | | X | |

[V] Morteza Mehrnoush, Meta | | | X |

[V] Masatomo Ouchi, Canon | | | X |

[V} Kazuto Yano, ATR | | | X |

[V] Jeongki Kim Ofinno | | | X |

[V] Atsushi Shirakawa, Sharp | | | X |

[V] Pei Zhou, OPPO | | | X |

[V] Xiangxin Gu, Unisoc | X | | |

[V] Yuki Tsujimaru Canon | X | | |

[V] Ming Gan Huawei | X | | |

[V] Jinsoo Choi LG | X | | |

[V] Akira Kishida, NTT | X | | |

[V] Sungjin Park, Senscomm | | | X |

[V] Greg Geonjung Ko WILUS | | | X |

[V] Tongxin Shu Huawei | X | | |

[V] Ross Jian Yu Huawei | X | | |

[A] Zhi Mao, Huawei | X | | | INVALID VOTE: NON VOTER

[V] BO SUN, Sanechips | | | X |

[V]Guogang Huang Huawei | X | | |

[V] Jason Yuchen Guo Huawei | X | | |

[V] Mengshi Hu Huawei | X | | |

[NV] Yunsi Ma HiSilicon Shanghai | X | | | INVALID VOTE: NON VOTER

[V]Yousi Lin Huawei | X | | |

[V] Lei Huang Huawei | X | | |

[V] Yunbo Li, Huawei | X | | |

[V] Lan Peng Huawei | X | | |

[V] Frank Chien-Fang Hsu, Mediatek | | | X |

[V] Harry Hao Wang Tencent | | | X |

[V] Zhenguo Du, Huawei | X | | |

[V] Hongjia Su Huawei | X | | |

[V] Liuming Lu OPPO | | | X |

[V] Shimi Shilo Huawei | X | | |

[V] Stephane Baron Canon | | | X |

[V] Patrice NEZOU, Canon | | | X |

[V] Daniel Verenzuela Sony | | | X |

[V] Thomas Handte Sony | | | X |

[V] Romain GUIGNARD Canon | | | X |

[V] Pascal Viger, Canon | | | X |

[V] Mikael Lorgeoux Canon | | | X |

[V] Allert van Zelst, Qualcomm | | X | |

[V] Kazi Huq, Ofinno | | | X |

[V] Mahmoud Kamel InterDigital | | | X |

[V] Leonardo Lanante, Ofinno | | | X |

[V] Jiayi Zhang, Ofinno | X | | |

[V] Carol Ansley Cox | | | X |

[V] Jung Hoon Suh Huawei | X | | |

[V] Serhat Erkucuk, Ofinno | | | X |

[V] John Wullert, Peraton Labs | X | | |

[V] Zinan Lin, InterDigital | | | X |

[V] Subir Peraton Labs | | | X |

[V] Yan Xin Huawei | X | | |

[V] Joseph Levy, InterDigital | | X | |

[V] Lili Hervieu CableLabs | X | | |

[V]John Yi.Spreadtrum | | | X | INVALID VOTE: NON VOTER

[V] Sang Kim LGE | | | X |

[V] Wook Bong Lee | | | X |

Yonggang Fang | | X | |

[V] Xiaogang Chen ZEKU | | | X |

[V] Abhishek Patil Qualcomm | | X | |

Jarkko Kneckt | X | | |

[V] Gaurang Naik, Qualcomm Inc. | | X | |

[V] Minyoung Park, Intel | | X | |

[V] Sameer Vermani Qualcomm | | X | |

[V] George Cherian Qualcomm | | X | |

[V] Yanjun Sun Qualcomm | | X | |

[V] Brian Hart Cisco Systems | | X | |

[V] Li-Hsiang Sun, Mediatek | | | X |

[V] Tianyu Wu Apple | | | X |

[V] Bin Tian Qualcomm | | X | |

[V] Sai Nanda [Synaptics] | | | X |

[V] James Yee, MediaTek | | | X |

[V] Binita Gupta, Meta | | X | |

[V] Duncan Ho Qualcomm | | X | |

[V] Dibakar Das, Intel | | | X |

[V] Yongho Seok MediaTek | | X | |

Matthew Fischer | | X | |

[V}Kanke Wu Qualcomm | | X | |

[NV] Zhiqun Leo Liu, Qualcomm | | X | |

[Mediatek] Gabor Bajko | | X | |

Yong Liu | X | | |

[V] Youhan Kim, Qualcomm | | X | |

[V] Prabodh Varshney Nokia | X | | |

[V] Mike Montemurro Huawei | X | | |

[V] Osama Aboul-Magd Huawei | X | | |

**Results for Motion 454**

Calculated Results : 27Y, 23N, 28A, [54%]

Amended Results : 26Y, 23N, 27A, [53%]

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---------------------------------------------

[V] Abdel Karim Ajami, Qualcomm | | X | |

[V] Vishnu V Ratnam, Samsung Research America | X | | |

[V] Al Petrick InterDigital | | X | |

[V] Dong Wei, NXP | | | X |

[V] Rubayet Shafin, Samsung Research America | | | X |

[V] Boon Loong Ng Samsung Research America | | | X |

Ian Sherlock | X | | |

[V] Morteza Mehrnoush, Meta | | | X |

[V] Masatomo Ouchi, Canon | | | X |

[V} Kazuto Yano, ATR | | | X |

[V] Xiangxin Gu, Unisoc | X | | |

[V]Chenchen Liu Huawei | X | | |

[V] Yuki Tsujimaru Canon | | | X |

[V] Ming Gan Huawei | X | | |

[V] Jinsoo Choi LG | X | | |

[V] Akira Kishida, NTT | X | | |

[V] Sungjin Park, Senscomm | | | X |

[V] Tongxin Shu Huawei | X | | |

[V] Ross Jian Yu Huawei | X | | |

[V] BO SUN, Sanechips | | | X |

[V]Guogang Huang Huawei | X | | |

[V] Jason Yuchen Guo Huawei | X | | |

[V] Mengshi Hu Huawei | X | | |

[NV] Yunsi Ma HiSilicon Shanghai | X | | | INVALID VOTE: NON VOTER

[V]Yousi Lin Huawei | X | | |

[V] Lei Huang Huawei | X | | |

[V] Yunbo Li, Huawei | X | | |

[V]Lei Zhou, New H3C Technologies | X | | |

[V] Lan Peng Huawei | X | | |

[V] Hongjia Su Huawei | X | | |

[V] Liuming Lu OPPO | | | X |

[V] Shimi Shilo Huawei | X | | |

[V] Patrice NEZOU, Canon | | | X |

[V] Arik Klein Huawei | | | X |

[V] Daniel Verenzuela Sony | | | X |

[V] Pascal Viger, Canon | | | X |

[V] Massinissa Lalam Sagemcom | | X | |

[V] Mikael Lorgeoux Canon | | | X |

[V] Allert van Zelst, Qualcomm | | X | |

[V] Kazi Huq, Ofinno | | X | |

[V] Junghoon Suh Huawei | X | | |

[V] Tuncer Baykas, Ofinno | | | X |

[V] Jiayi Zhang, Ofinno | X | | |

[V] Carol Ansley Cox | | | X |

[V] Serhat Erkucuk, Ofinno | | | X |

[V] John Wullert, Peraton Labs | X | | |

[V] Zinan Lin, InterDigital | | | X |

[V] Subir Peraton Labs | | | X |

[V] Joseph Levy, InterDigital | | X | |

[V] Lili Hervieu CableLabs | X | | |

[V]John Yi.Spreadtrum | | | X | INVALID VOTE: NON VOTER

[V] Sang Kim LGE | | | X |

[V] Wook Bong Lee | | | X |

[V] Kaiying Lu Mediatek USA | | X | |

[V] Xiaogang Chen ZEKU | | X | |

[V] Abhishek Patil Qualcomm | | X | |

[V] Gaurang Naik, Qualcomm Inc. | | X | |

[V] Minyoung Park, Intel | | X | |

[V] George Cherian Qualcomm | | X | |

[V] Yanjun Sun Qualcomm | | X | |

[V] Brian Hart Cisco Systems | | | X |

[V] Bin Tian Qualcomm | | X | |

[V] Chao-Chun Wang MediaTek | | X | |

[V] Binita Gupta, Meta | | X | |

[V] Duncan Ho Qualcomm | | X | |

[V] Dibakar Das, Intel | | | X |

[V] Yongho Seok MediaTek | | X | |

Matthew Fischer | | X | |

[V}Kanke Wu Qualcomm | | X | |

[NV] Zhiqun Leo Liu, Qualcomm | | X | |

Yong Liu | X | | |

[Mediatek] Gabor Bajko | | | X |

[V] Srinivas Kandala Samsung | | | X |

Paul Cheng | | X | |

[V] Youhan Kim, Qualcomm | | X | |

[V] Prabodh Varshney Nokia | | | X |

[V] Mike Montemurro Huawei | X | | |

[V] Osama Aboul-Magd Huawei | X | | |

**Results for Motion 455**

Calculated Results : 25Y, 26N, 35A, [49%]

Amended Results : 24Y, 26N, 34A, [48%]

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[V] Abdel Karim Ajami, Qualcomm | | X | |

[V] Vishnu V Ratnam, Samsung Research America | X | | |

[V] Al Petrick InterDigital | | | X |

[V] Dong Wei, NXP | | | X |

[V] Rubayet Shafin, Samsung Research America | | | X |

[V] Boon Loong Ng Samsung Research America | | | X |

Ian Sherlock | X | | |

[V] Sanghyun Kim WILUS Inc. | | | X |

[V] Masatomo Ouchi, Canon | | | X |

[V} Kazuto Yano, ATR | | | X |

[V] SunHee Baek LGE | | | X |

[V] Jinyoung Chun, LG | | | X |

[V] Pei Zhou, OPPO | | X | |

[V] Xiangxin Gu, Unisoc | | | X |

[V]Chenchen Liu Huawei | X | | |

[NV]Yajun CHENG-Xiaomi | | | X | INVALID VOTE: NON VOTER

[V] Ming Gan Huawei | X | | |

[V] Jinsoo Choi LG | X | | |

[V] Akira Kishida, NTT | X | | |

[V] Sungjin Park, Senscomm | | | X |

[V] Greg Geonjung Ko WILUS | | | X |

[V] Ross Jian Yu Huawei | X | | |

[A] Zhi Mao, Huawei | X | | | INVALID VOTE: NON VOTER

[V] BO SUN, Sanechips | | | X |

[V]Guogang Huang Huawei | X | | |

[V] Jason Yuchen Guo Huawei | X | | |

[V]Steven Qi Wang Huawei | X | | |

[V] Mengshi Hu Huawei | X | | |

[V]Yousi Lin Huawei | X | | |

[V] Yunbo Li, Huawei | X | | |

[V]Lei Zhou, New H3C Technologies | X | | |

[V] Lan Peng Huawei | X | | |

[V] Harry Hao Wang Tencent | | | X |

[V] Zhenguo Du, Huawei | X | | |

[V] Hongjia Su Huawei | X | | |

[V] Liuming Lu OPPO | | | X |

[V] Shimi Shilo Huawei | X | | |

[V] Stephane Baron Canon | | | X |

[V] Patrice NEZOU, Canon | | | X |

[V] Arik Klein Huawei | | | X |

[V] Daniel Verenzuela Sony | | X | |

[V] Thomas Handte Sony | | | X |

[V] Stephen McCann, Huawei | X | | |

[V] Romain GUIGNARD Canon | | | X |

[V] Massinissa Lalam Sagemcom | | X | |

[V] Mikael Lorgeoux Canon | | | X |

[V] Allert van Zelst, Qualcomm | | X | |

[V] Kazi Huq, Ofinno | | | X |

[V] Mahmoud Kamel InterDigital | | | X |

[V] Leonardo Lanante, Ofinno | | X | |

[V] Junghoon Suh Huawei | X | | |

[V] Carol Ansley Cox | | | X |

[V] Serhat Erkucuk, Ofinno | | | X |

[V] Hanqing Lou InterDigital | | X | |

[V] John Wullert, Peraton Labs | X | | |

[V] Zinan Lin, InterDigital | | | X |

[V] Subir Peraton Labs | | | X |

[V] Yan Xin Huawei | X | | |

[V] Joseph Levy, InterDigital | | X | |

[V] Sang Kim LGE | | | X |

[V] Wook Bong Lee | | | X |

[V] Xiaogang Chen ZEKU | | X | |

[V] Abhishek Patil Qualcomm | | X | |

Jarkko Kneckt | X | | |

[V] Gaurang Naik, Qualcomm Inc. | | X | |

[V] Minyoung Park, Intel | | X | |

[V] George Cherian Qualcomm | | X | |

[V] Yanjun Sun Qualcomm | | X | |

[V] Brian Hart Cisco Systems | | X | |

[V] Tianyu Wu Apple | | | X |

[V] Bin Tian Qualcomm | | X | |

[V] James Yee, MediaTek | | X | |

[V] Binita Gupta, Meta | | X | |

[V] Duncan Ho Qualcomm | | X | |

[V] Dibakar Das, Intel | | | X |

[V] Yongho Seok MediaTek | | X | |

Matthew Fischer | | X | |

[V}Kanke Wu Qualcomm | | X | |

[NV] Zhiqun Leo Liu, Qualcomm | | X | |

Yong Liu | | | X |

[V] Youhan Kim, Qualcomm | | X | |

[Mediatek] Gabor Bajko | | X | |

[V] Srinivas Kandala Samsung | | | X |

[V] Paul Cheng, MediaTek | | X | |

[V] Prabodh Varshney Nokia | | | X |

[V] Osama Aboul-Magd Huawei | X | | |

* Discussions of the Technical Submissions**: CRs**
  + [1423r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1423-00-00be-eht-smps.docx) EHT SMPS Xiaogang Chen

The presentation of this document is not finished due to time limit.

* Adjourn at 12:00